

V_{DSS}	30V
R_{DS(on)}(typ.)	6.2mΩ
I_D	65A
P_D	54W

Outline

P PAK 5X6



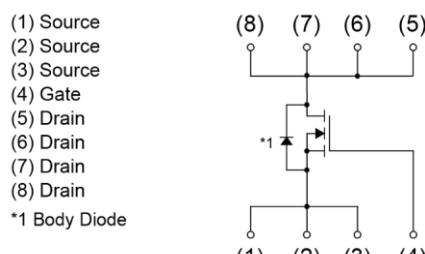
Features

- 1) Low on - resistance
- 2) High power package (P PAK5X6)
- 3) Pb-free lead plating ; RoHS compliant
- 4) Halogen free
- 5) 100% Rg and UIS tested

Application

Switching

Inner circuit



Packaging specifications

Type	Packing	Embossed Tape
Reel size (mm)	330	
Tape width (mm)	12	
Basic ordering unit (pcs)	5000	
Taping code	D5	
Marking	AD30N65D5	

Absolute maximum ratings ($T_a = 25^\circ\text{C}$)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	± 20	V
I _D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	65	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	41	A
I _{DM}	Drain Current – Pulsed ¹	260	A
EAS	Single Pulse Avalanche Energy ²	45	mJ
IAS	Single Pulse Avalanche Current ²	30	A
P _D	Power Dissipation ($T_c=25^\circ\text{C}$)	54	W
	Power Dissipation – Derate above 25°C	0.43	W/ $^\circ\text{C}$
T _{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T _J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C}/\text{W}$
R _{θJC}	Thermal Resistance Junction to Case	---	2.3	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Static State Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.04	---	$\text{mV}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ³	$V_{\text{GS}}=10\text{V}$, $I_D=16\text{A}$	---	6.2	7.2	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=8\text{A}$	---	8.9	11.5	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.2	1.6	2.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-4	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=8\text{A}$	---	9.5	---	S

Dynamic Characteristics

Q_g	Total Gate Charge ^{3,4}	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=20\text{A}$	---	7.5	12	nC
Q_{gs}	Gate-Source Charge ^{3,4}		---	4.5	8	
Q_{gd}	Gate-Drain Charge ^{3,4}		---	1.3	2.6	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{3,4}	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$ $I_D=15\text{A}$	---	4.8	9	ns
T_r	Rise Time ^{3,4}		---	12.5	24	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{3,4}		---	27.6	52	
T_f	Fall Time ^{3,4}		---	8.2	16	
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	680	1000	pF
C_{oss}	Output Capacitance		---	150	220	
C_{rss}	Reverse Transfer Capacitance		---	70	105	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	2.7	5.4	Ω

Guaranteed Avalanche Energy

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	$V_{\text{DD}}=25\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=15\text{A}$	12	---	---	mJ

Drain-Source Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	65	A
I_{SM}	Pulsed Source Current ³		---	---	130	A
V_{SD}	Diode Forward Voltage ³	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V
t_{rr}	Reverse Recovery Time	$V_{\text{GS}}=0\text{V}$, $I_s=10\text{A}$, $di/dt=100\text{A}/\mu\text{s}$	---	8.1	---	ns
Q_{rr}	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	1.6	---	nC

Note :

1.Repetitive Rating : Pulsed width limited by maximum junction temperature.

2. $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=30\text{A}$, $R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.

3.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

4.Essentially independent of operating temperature.

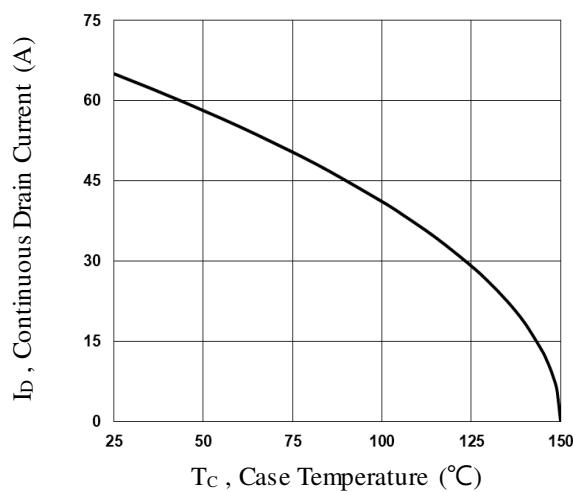


Fig.1 Continuous Drain Current vs. T_C

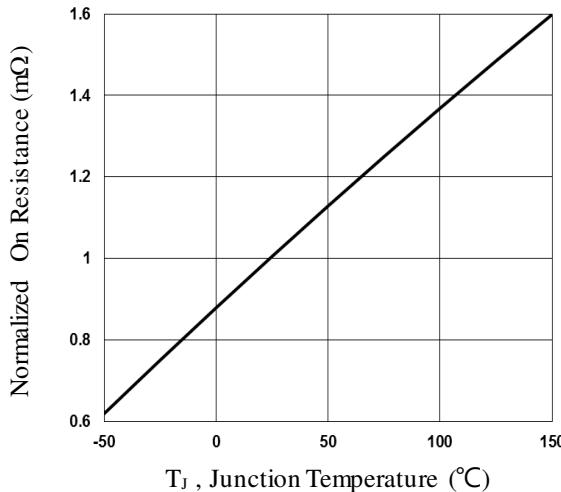


Fig.2 Normalized RDSON vs. T_J

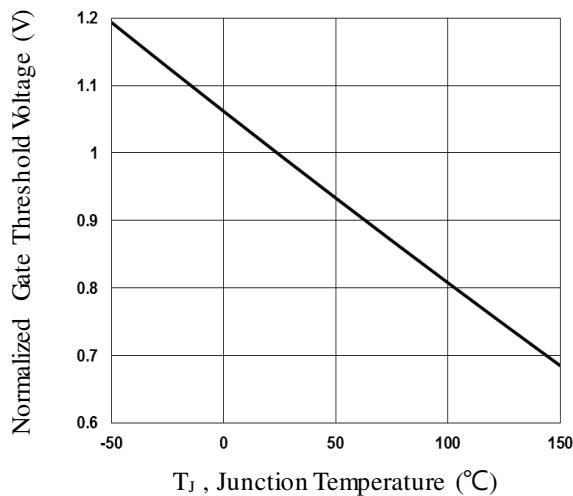


Fig.3 Normalized V_{th} vs. T_J

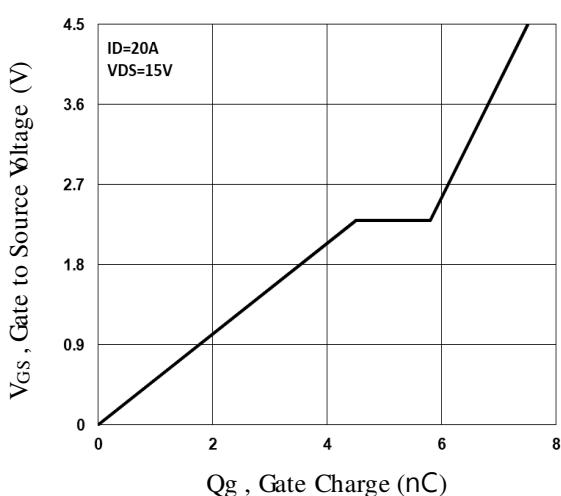


Fig.4 Gate Charge Waveform

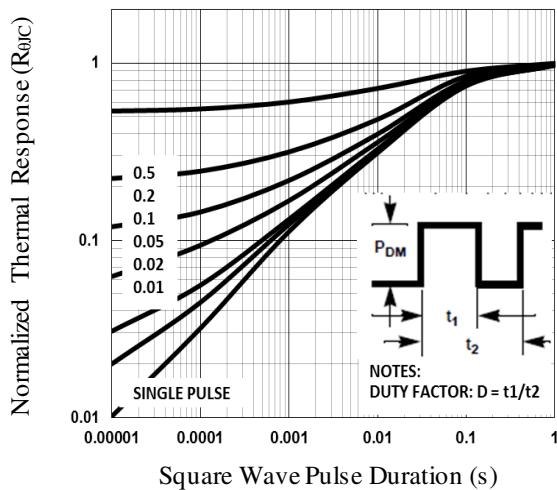


Fig.5 Normalized Transient Impedance

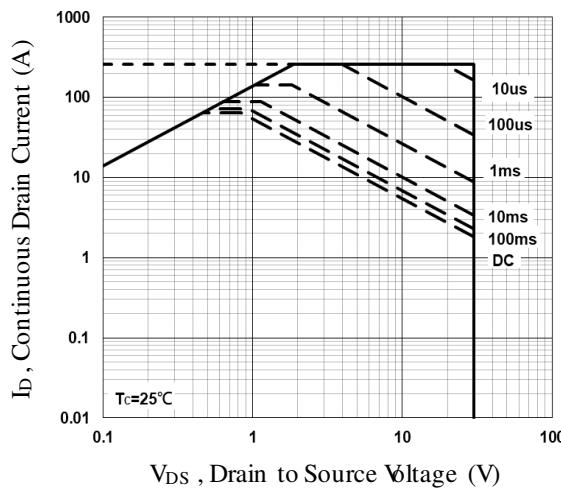


Fig.6 Maximum Safe Operation Area

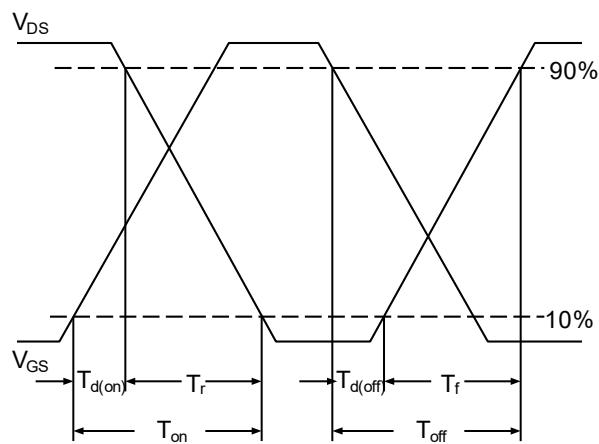


Fig.7 Switching Time Waveform

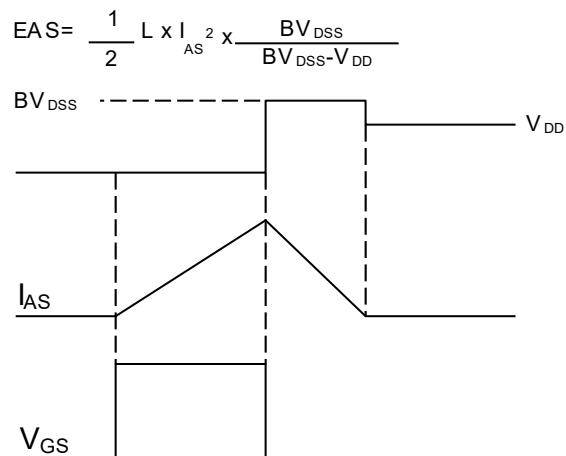
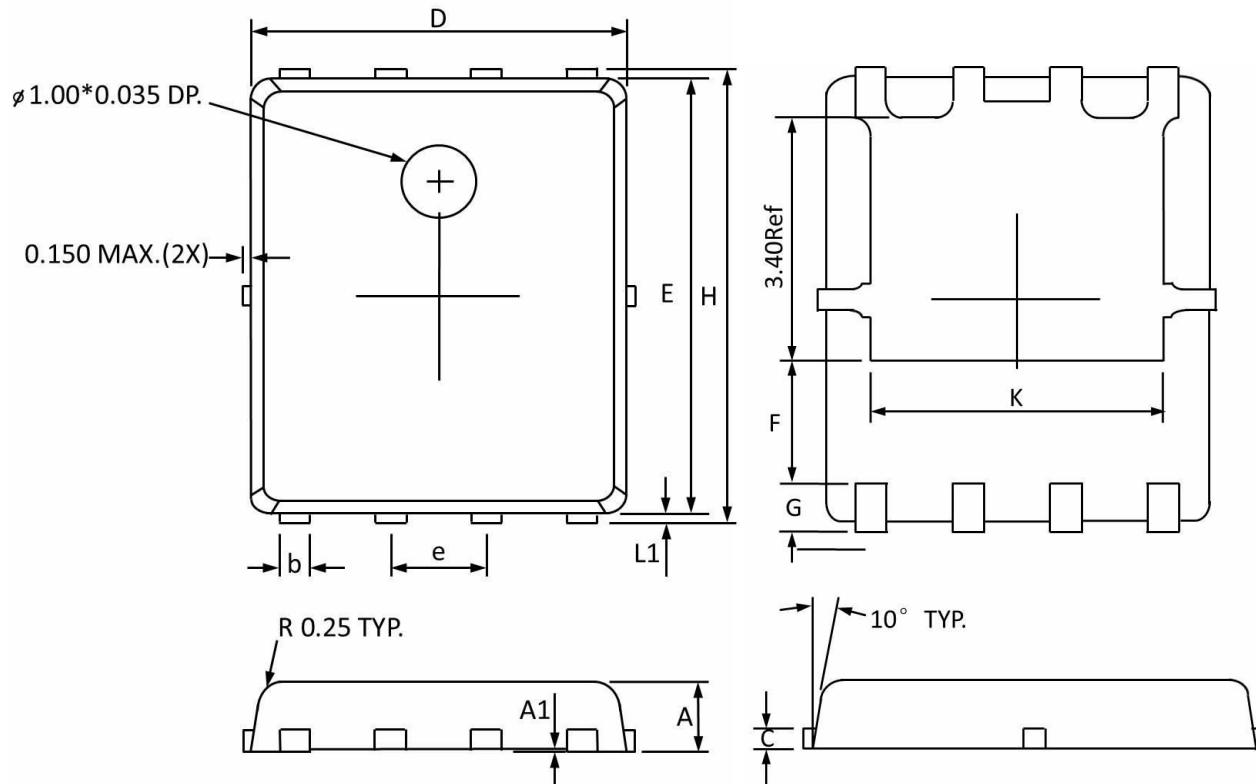


Fig.8 EAS Waveform

PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.800	1.000	0.032	0.039
A1	0.000	0.005	0.000	0.000
b	0.350	0.490	0.014	0.019
C	0.254 Ref		0.254 Ref	
D	4.900	5.100	0.193	0.200
E	5.700	5.900	0.225	0.232
e	1.27 BSC		1.27 BSC	
F	1.400 Ref		1.400 Ref	
G	0.600 Ref		0.600 Ref	
H	5.950	6.200	0.235	0.244
L1	0.100	0.180	0.004	0.007
K	4.000 Ref		4.000 Ref	